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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8052
Core Size	8-Bit
Speed	8.38MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	DMA, PSM, PWM, Temp Sensor, WDT
Number of I/O	32
Program Memory Size	62KB (62K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.25K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-QFP
Supplier Device Package	80-PQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/aduc842bsz62-3

Parameter	V_{DD} = 5 V	V_{DD} = 3 V	Unit	Test Conditions/Comments
LOGIC INPUTS[4]				
INPUT VOLTAGES				
All Inputs Except SCLOCK, SDATA, RESET, and XTAL1				
VINL, Input Low Voltage	0.8	0.4	V max	
VINH, Input High Voltage	2.0	2.0	V min	
SDATA				
VINL, Input Low Voltage	0.8	0.8	V max	
VINH, Input High Voltage	2.0	2.0	V min	
SCLOCK and RESET ONLY[4]				
(Schmitt-Triggered Inputs)				
V_{T+}	1.3	0.95	V min	
	3.0	0.25	V max	
V_{T-}	0.8	0.4	V min	
	1.4	1.1	V max	
$V_{T+} - V_{T-}$	0.3	0.3	V min	
	0.85	0.85	V max	
CRYSTAL OSCILLATOR				
Logic Inputs, XTAL1 Only				
V_{INL}, Input Low Voltage	0.8	0.4	V typ	
V_{INH}, Input High Voltage	3.5	2.5	V typ	
XTAL1 Input Capacitance	18	18	pF typ	
XTAL2 Output Capacitance	18	18	pF typ	
MCU CLOCK RATE	16.78	8.38	MHz max	ADuC842/ADuC843 Only
	20	8.38	MHz max	ADuC841 Only
DIGITAL OUTPUTS				
Output High Voltage (V_{OH})	2.4		V min	V_{DD} = 4.5 V to 5.5 V
	4		V typ	I_{SOURCE} = 80 µA
		2.4	V min	V_{DD} = 2.7 V to 3.3 V
		2.6	V typ	I_{SOURCE} = 20 µA
Output Low Voltage (V_{OL})				
ALE, Ports 0 and 2	0.4	0.4	V max	I_{SINK} = 1.6 mA
	0.2	0.2	V typ	I_{SINK} = 1.6 mA
Port 3	0.4	0.4	V max	I_{SINK} = 4 mA
SCLOCK/SDATA	0.4	0.4	V max	I_{SINK} = 8 mA, I^2C Enabled
Floating State Leakage Current[4]	±10	±10	µA max	
	±1	±1	µA typ	
STARTUP TIME				At any core CLK
At Power-On	500	500	ms typ	
From Idle Mode	100	100	µs typ	
From Power-Down Mode				
Wake-up with $\overline{INT0}$ Interrupt	150	400	µs typ	
Wake-up with SPI/I^2C Interrupt	150	400	µs typ	
Wake-up with External RESET	150	400	µs typ	
After External RESET in Normal Mode	30	30	ms typ	
After WDT Reset in Normal Mode	3	3	ms typ	Controlled via WDCON SFR

ABSOLUTE MAXIMUM RATINGS

Table 2. T_A = 25°C, unless otherwise noted

Parameter	Rating
AV_{DD} to DV_{DD}	−0.3 V to +0.3 V
AGND to DGND	−0.3 V to +0.3 V
DV_{DD} to DGND, AV_{DD} to AGND	−0.3 V to +7 V
Digital Input Voltage to DGND	−0.3 V to DV_{DD} + 0.3 V
Digital Output Voltage to DGND	−0.3 V to DV_{DD} + 0.3 V
V_{REF} to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Inputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Operating Temperature Range, Industrial ADuC841BS, ADuC842BS, ADuC843BS, ADuC841BCP, ADuC842BCP, ADuC843BCP	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
θ_{JA} Thermal Impedance (ADuC84xBS)	90°C/W
θ_{JA} Thermal Impedance (ADuC84xBCP)	52°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

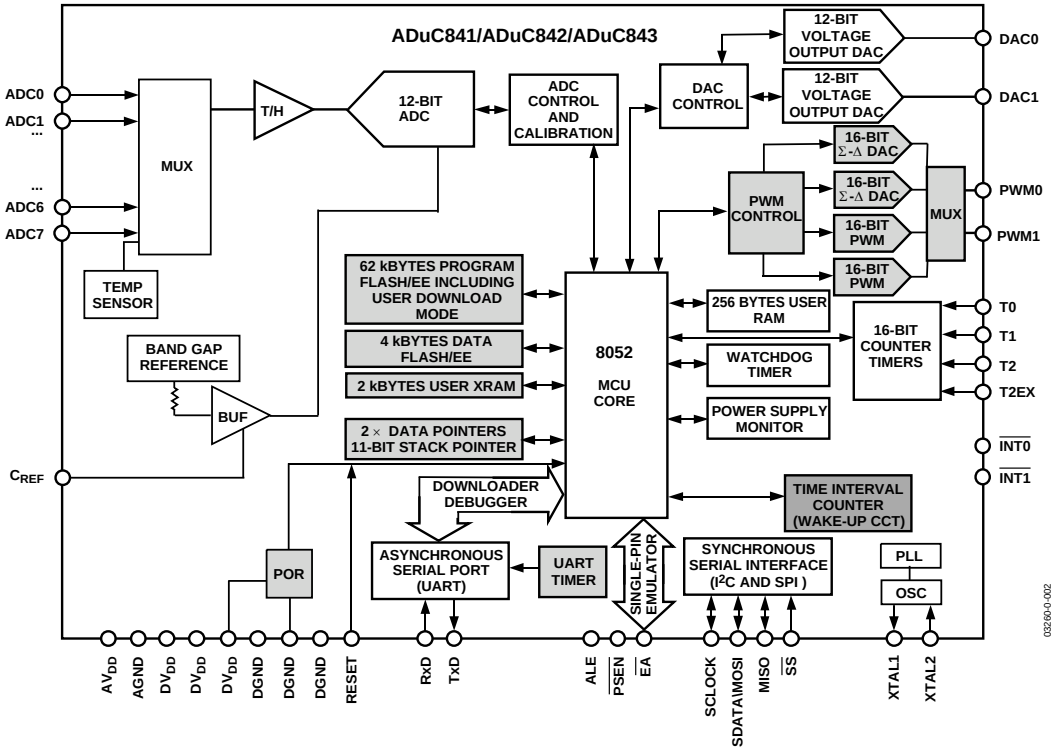

Figure 2. ADuC841/ADuC842/ADuC843 Block Diagram (Shaded Areas are Features Not Present on the ADuC812), No DACs on ADuC843, PLL on ADuC842/ADuC843 Only.

Pin No.	Mnemonic	Type[1]	Description
12	DAC1	O	Voltage Output from DAC1. This pin is a no connect on the ADuC843.
13	P1.4/ADC4		Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 4 (ADC4). Channel selection is via ADCCON2 SFR.
14	P1.5/ADC5/$\overline{SS}$	I	Input Port 1 (P1.5). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 5 (ADC5). Channel selection is via ADCCON2 SFR.
			Slave Select Input for the SPI Interface ($\overline{SS}$).
15	P1.3/ADC6	I	Input Port 1 (P1.3). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 6 (ADC6). Channel selection is via ADCCON2 SFR.
16	P1.7/ADC7	I	Input Port 1(P1.7). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 7 (ADC7). Channel selection is via ADCCON2 SFR.
17	RESET	I	Reset. Digital Input. A high level on this pin for 24 master clock cycles while the oscillator is running resets the device.
18	P3.0/RxD	I/O	Input/Output Port 3 (P3.0). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Receiver Data Input (Asynchronous) or Data Input/Output (Synchronous) of the Serial (UART) Port (RxD).
19	P3.1/TxD	I/O	Input/Output Port 3 (P3.1). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Transmitter Data Output (Asynchronous) or Clock Output (Synchronous) of the Serial (UART) Port (TxD).
20	P3.2/$\overline{INT0}$	I/O	Input/Output Port 3 (P3.2). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 0 ($\overline{INT0}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 0.
21	P3.3/$\overline{INT1}$/MISO/PWM1	I/O	Input/Output Port 3 (P3.3). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 1 ($\overline{INT1}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 1.
			SPI Master Input/Slave Output Data I/O Pin for SPI Serial Interface (MISO).
			PWM 1 Voltage Output (PWM1). See the CFG841/CFG842 register for further information.
22, 36, 51	DV_{DD}	P	Digital Positive Supply Voltage. 3 V or 5 V nominal.
23, 37, 38, 50	DGND	G	Digital Ground. DGND is the ground reference point for the digital circuitry.

Pin No.	Mnemonic	Type[1]	Description
46	P0.0/A0	I/O	Input/Output Port 0 (P0.0). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A0). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-ups when emitting 1s.
47	P0.1/A1	I/O	Input/Output Port 0 (P0.1). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A1). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
48	P0.2/A2	I/O	Input/Output Port 0 (P0.2). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A2). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
49	P0.3/A3	I/O	Input/Output Port 0 (P0.3). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A3). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
52	P0.4/A4	I/O	Input/Output Port 0 (P0.4). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A4). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
53	P0.5/A5	I/O	Input/Output Port 0 (P0.5). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A5). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
54	P0.6/A6	I/O	Input/Output Port 0 (P0.6). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A6). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
55	P0.7/A7	I/O	Input/Output Port 0 (P0.7). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A7). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
56	P1.0/ADC0/T2	I	Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input (ADC0). Channel selection is via ADCCON2 SFR. Timer 2 Digital Input (T2). Input to Timer/Counter 2. When enabled, Counter 2 is incremented in response to a 1-to-0 transition of the T2 input.
	EPAD		Exposed Pad. The LFCSP has an exposed pad that must be soldered to the metal plate on the printed circuit board (PCB) for mechanical reasons and to DGND.

[1] P = power, G = ground, I = input, O = output, and NC = no connect.

TYPICAL PERFORMANCE CHARACTERISTICS

The typical performance plots presented in this section illustrate typical performance of the ADuC841/ADuC842/ADuC843 under various operating conditions.

Figure 5 and Figure 6 show typical ADC integral nonlinearity (INL) errors from ADC Code 0 to Code 4095 at 5 V and 3 V supplies, respectively. The ADC is using its internal reference (2.5 V) and is operating at a sampling rate of 152 kHz; the typical worst-case errors in both plots are just less than 0.3 LSB. Figure 7 and Figure 8 also show ADC INL at a higher sampling rate of 400 kHz. Figure 9 and Figure 10 show the variation in worst-case positive (WCP) INL and worst-case negative (WCN) INL versus external reference input voltage.

Figure 11 and Figure 12 show typical ADC differential nonlinearity (DNL) errors from ADC Code 0 to Code 4095 at 5 V and 3 V supplies, respectively. The ADC is using its internal reference (2.5 V) and is operating at a sampling rate of 152 kHz; the typical worst-case errors in both plots are just less than 0.2 LSB. Figure 13 and Figure 14 show the variation in worst-case positive (WCP) DNL and worst-case negative (WCN) DNL versus external reference input voltage.

Figure 15 shows a histogram plot of 10,000 ADC conversion results on a dc input with V_{DD} = 5 V. The plot illustrates an excellent code distribution pointing to the low noise performance of the on-chip precision ADC.

Figure 16 shows a histogram plot of 10,000 ADC conversion results on a dc input for V_{DD} = 3 V. The plot again illustrates a very tight code distribution of 1 LSB with the majority of codes appearing in one output pin.

Figure 17 and Figure 18 show typical FFT plots for the parts. These plots were generated using an external clock input. The ADC is using its internal reference (2.5 V), sampling a full-scale, 10 kHz sine wave test tone input at a sampling rate of 149.79 kHz. The resulting FFTs shown at 5 V and 3 V supplies illustrate an excellent 100 dB noise floor, 71 dB signal-to-noise ratio (SNR), and THD greater than –80 dB.

Figure 19 and Figure 20 show typical dynamic performance versus external reference voltages. Again, excellent ac performance can be observed in both plots with some roll-off being observed as V_{REF} falls below 1 V.

Figure 21 shows typical dynamic performance versus sampling frequency. SNR levels of 71 dB are obtained across the sampling range of the parts.

Figure 22 shows the voltage output of the on-chip temperature sensor versus temperature. Although the initial voltage output at 25°C can vary from part to part, the resulting slope of −1. 4 mV/°C is constant across all parts.

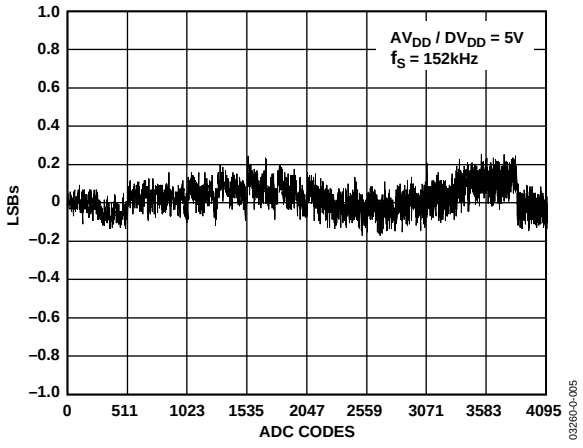

Figure 5. Typical INL Error, V_{DD} = 5 V, f_s = 152 kHz

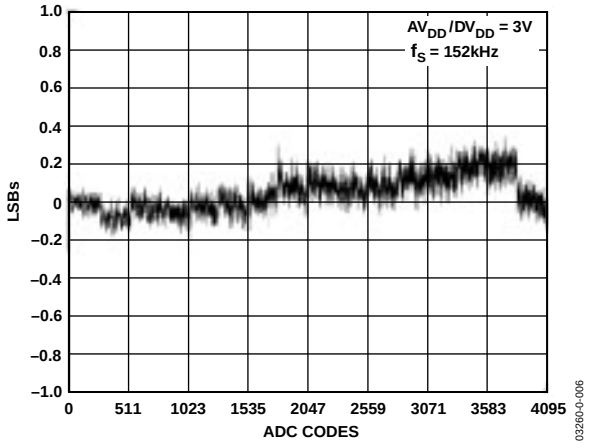

Figure 6. Typical INL Error, V_{DD} = 3 V, f_s = 152 kHz

Mnemonic	Description	Bytes	Cycles
XRL A,dir	Exclusive-OR indirect memory to A	2	2
XRL dir,#data	Exclusive-OR immediate data to direct	3	3
CLR A	Clear A	1	1
CPL A	Complement A	1	1
SWAP A	Swap nibbles of A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1
Data Transfer			
MOV A,Rn	Move register to A	1	1
MOV A,@Ri	Move indirect memory to A	1	2
MOV Rn,A	Move A to register	1	1
MOV @Ri,A	Move A to indirect memory	1	2
MOV A,dir	Move direct byte to A	2	2
MOV A,#data	Move immediate to A	2	2
MOV Rn,#data	Move register to immediate	2	2
MOV dir,A	Move A to direct byte	2	2
MOV Rn, dir	Move register to direct byte	2	2
MOV dir, Rn	Move direct to register	2	2
MOV @Ri,#data	Move immediate to indirect memory	2	2
MOV dir,@Ri	Move indirect to direct memory	2	2
MOV @Ri,dir	Move direct to indirect memory	2	2
MOV dir,dir	Move direct byte to direct byte	3	3
MOV dir,#data	Move immediate to direct byte	3	3
MOV DPTR,#data	Move immediate to data pointer	3	3
MOVC A,@A+DPTR	Move code byte relative DPTR to A	1	4
MOVC A,@A+PC	Move code byte relative PC to A	1	4
MOVX A,@Ri	Move external (A8) data to A	1	4
MOVX A,@DPTR	Move external (A16) data to A	1	4
MOVX @Ri,A	Move A to external data (A8)	1	4
MOVX @DPTR,A	Move A to external data (A16)	1	4
PUSH dir	Push direct byte onto stack	2	2
POP dir	Pop direct byte from stack	2	2
XCH A,Rn	Exchange A and register	1	1
XCH A,@Ri	Exchange A and indirect memory	1	2
XCHD A,@Ri	Exchange A and indirect memory nibble	1	2
XCH A,dir	Exchange A and direct byte	2	2
Boolean			
CLR C	Clear carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement carry	1	1
CPL bit	Complement direct bit	2	2
ANL C,bit	AND direct bit and carry	2	2
ANL C,/bit	AND direct bit inverse to carry	2	2
ORL C,bit	OR direct bit and carry	2	2
ORL C,/bit	OR direct bit inverse to carry	2	2
MOV C,bit	Move direct bit to carry	2	2
MOV bit,C	Move carry to direct bit	2	2

The ADC incorporates a successive approximation architecture (SAR) involving a charge-sampled input stage. Figure 30 shows the equivalent circuit of the analog input section. Each ADC conversion is divided into two distinct phases, as defined by the position of the switches in Figure 30. During the sampling phase (with SW1 and SW2 in the track position), a charge proportional to the voltage on the analog input is developed across the input sampling capacitor. During the conversion phase (with both switches in the hold position), the capacitor DAC is adjusted via internal SAR logic until the voltage on Node A is 0, indicating that the sampled charge on the input capacitor is balanced out by the charge being output by the capacitor DAC. The final digital value contained in the SAR is then latched out as the result of the ADC conversion. Control of the SAR and timing of acquisition and sampling modes is handled automatically by built-in ADC control logic. Acquisition and conversion times are also fully configurable under user control.

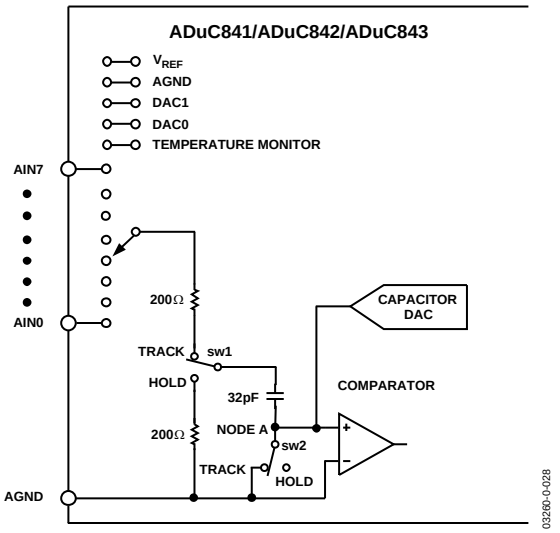

Figure 30. Internal ADC Structure

Note that whenever a new input channel is selected, a residual charge from the 32 pF sampling capacitor places a transient on the newly selected input. The signal source must be capable of recovering from this transient before the sampling switches go into hold mode. Delays can be inserted in software (between channel selection and conversion request) to account for input stage settling, but a hardware solution alleviates this burden from the software design task and ultimately results in a cleaner system implementation. One hardware solution is to choose a very fast settling op amp to drive each analog input. Such an op amp would need to fully settle from a small signal transient in less than 300 ns in order to guarantee adequate settling under all software configurations. A better solution, recommended for use with any amplifier, is shown in Figure 31. Though at first glance the circuit in Figure 31 may look like a simple antialiasing filter, it actually serves no such purpose since its corner frequency is well above the Nyquist frequency, even at a 200 kHz sample rate. Though the R/C does help to reject some incoming high frequency noise, its primary function is to ensure that the transient demands of the ADC input stage are met.

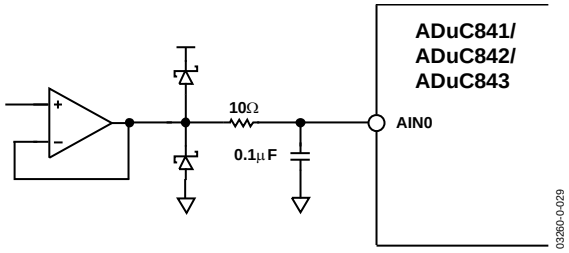

Figure 31. Buffering Analog Inputs

It does so by providing a capacitive bank from which the 32 pF sampling capacitor can draw its charge. Its voltage does not change by more than one count (1/4096) of the 12-bit transfer function when the 32 pF charge from a previous channel is dumped onto it. A larger capacitor can be used if desired, but not a larger resistor (for reasons described below). The Schottky diodes in Figure 31 may be necessary to limit the voltage applied to the analog input pin per the Absolute Maximum Ratings. They are not necessary if the op amp is powered from the same supply as the part since in that case the op amp is unable to generate voltages above V_{DD} or below ground. An op amp of some kind is necessary unless the signal source is very low impedance to begin with. DC leakage currents at the parts' analog inputs can cause measurable dc errors with external source impedances as low as 100 Ω or so. To ensure accurate ADC operation, keep the total source impedance at each analog input less than 61 Ω. The Table 11 illustrates examples of how source impedance can affect dc accuracy.

Table 11. Source Impedance and DC Accuracy

Source Impedance Ω	Error from 1 μA Leakage Current	Error from 10 μA Leakage Current
61	61 μV = 0.1 LSB	610 μV = 1 LSB
610	610 μV = 1 LSB	6.1 mV = 10 LSB

Although Figure 31 shows the op amp operating at a gain of 1, one can, of course, configure it for any gain needed. Also, one can just as easily use an instrumentation amplifier in its place to condition differential signals. Use an amplifier that is capable of delivering the signal (0 V to V_{REF}) with minimal saturation. Some single-supply rail-to-rail op amps that are useful for this purpose are described in Table 12. Check Analog Devices website www.analog.com for details on these and other op amps and instrumentation amps.

If using the temperature sensor as the ADC input, the ADC should be configured to use an ADCCLK of MCLK/32 and four acquisition clocks.

Increasing the conversion time on the temperature monitor channel improves the accuracy of the reading. To further improve the accuracy, an external reference with low temperature drift should also be used.

ADC DMA Mode

The on-chip ADC has been designed to run at a maximum conversion speed of 2.38 µs (420 kHz sampling rate). When converting at this rate, the ADuC841/ADuC842/ADuC843 MicroConverter® has 2 µs to read the ADC result and to store the result in memory for further postprocessing; otherwise the next ADC sample could be lost. In an interrupt driven routine, the MicroConverter would also have to jump to the ADC interrupt service routine, which also increases the time required to store the ADC results. In applications where the parts cannot sustain the interrupt rate, an ADC DMA mode is provided.

To enable DMA mode, Bit 6 in ADCCON2 (DMA) must be set, which allows the ADC results to be written directly to a 16 MByte external static memory SRAM (mapped into data memory space) without any interaction from the core of the part. This mode allows the part to capture a contiguous sample stream at full ADC update rates (420 kHz).

Typical DMA Mode Configuration Example

Setting the parts to DMA mode consists of the following steps:

1. The ADC must be powered down. This is done by ensuring that MD1 and MD0 are both set to 0 in ADCCON1.
2. The DMA address pointer must be set to the start address of where the ADC results are to be written. This is done by writing to the DMA mode address pointers DMAL, DMAH, and DMAP. DMAL must be written to first, followed by DMAH, and then by DMAP.
3. The external memory must be preconfigured. This consists of writing the required ADC channel IDs into the top four bits of every second memory location in the external SRAM, starting at the first address specified by the DMA address pointer. Because the ADC DMA mode operates independently from the ADuC841/ADuC842/ADuC843 core, it is necessary to provide it with a stop command. This is done by duplicating the last channel ID to be converted followed by 1111 into the next channel selection field. A typical preconfiguration of external memory is shown in Figure 34.

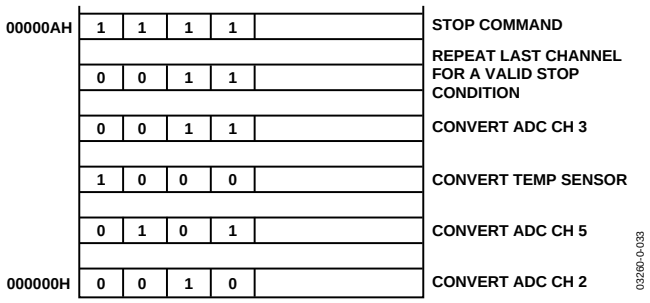

Figure 34. Typical DMA External Memory Preconfiguration

4. The DMA is initiated by writing to the ADC SFRs in the following sequence:
   a. ADCCON2 is written to enable the DMA mode, that is, MOV ADCCON2, #40H; DMA mode enabled.
   b. ADCCON1 is written to configure the conversion time and power-up of the ADC. It can also enable Timer 2 driven conversions or external triggered conversions if required.
   c. ADC conversions are initiated. This is done by starting single conversions, starting Timer 2, running for Timer 2 conversions, or receiving an external trigger.

When the DMA conversions are complete, the ADC interrupt bit, ADCI, is set by hardware, and the external SRAM contains the new ADC conversion results as shown in Figure 35. Note that no result is written to the last two memory locations.

When the DMA mode logic is active, it takes the responsibility of storing the ADC results away from both the user and the core logic of the part. As the DMA interface writes the results of the ADC conversions to external memory, it takes over the external memory interface from the core. Thus, any core instructions that access the external memory while DMA mode is enabled does not get access to the external memory. The core executes the instructions, and they take the same time to execute, but they cannot access the external memory.

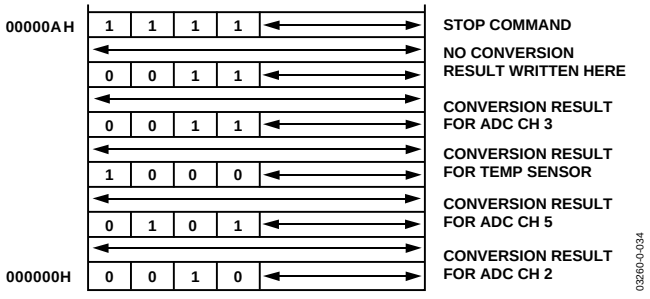

Figure 35. Typical External Memory Configuration Post ADC DMA Operation

The DMA logic operates from the ADC clock and uses pipelining to perform the ADC conversions and to access the external memory at the same time. The time it takes to perform one ADC conversion is called a DMA cycle. The actions performed by the logic during a typical DMA cycle are shown in Figure 36.

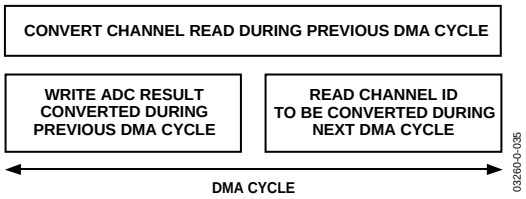

Figure 36. DMA Cycle

Figure 36 shows that during one DMA cycle, the following actions are performed by the DMA logic:

1. An ADC conversion is performed on the channel whose ID was read during the previous cycle.
2. The 12-bit result and the channel ID of the conversion performed in the previous cycle is written to the external memory.
3. The ID of the next channel to be converted is read from external memory.

For the previous example, the complete flow of events is shown in Figure 36. Because the DMA logic uses pipelining, it takes three cycles before the first correct result is written out.

Micro Operation during ADC DMA Mode

During ADC DMA mode, the MicroConverter core is free to continue code execution, including general housekeeping and communication tasks. However, note that MCU core accesses to Ports 0 and 2 (which of course are being used by the DMA controller) are gated off during the ADC DMA mode of operation. This means that even though the instruction that accesses the external Ports 0 or 2 appears to execute, no data is seen at these external ports as a result. Note that during DMA to the internally contained XRAM, Ports 0 and 2 are available for use.

The only case in which the MCU can access XRAM during DMA is when the internal XRAM is enabled and the section of RAM to which the DMA ADC results are being written to lies in an external XRAM. Then the MCU can access the internal XRAM only. This is also the case for use of the extended stack pointer.

The MicroConverter core can be configured with an interrupt to be triggered by the DMA controller when it has finished filling the requested block of RAM with ADC results, allowing the service routine for this interrupt to postprocess data without any real-time timing constraints.

ADC Offset and Gain Calibration Coefficients

The ADuC841/ADuC842/ADuC843 have two ADC calibration coefficients, one for offset calibration and one for gain calibration. Both the offset and gain calibration coefficients are 14-bit words, and are each stored in two registers located in the special function register (SFR) area. The offset calibration coefficient is divided into ADCOFSH (six bits) and ADCOFSL (8 bits), and the gain calibration coefficient is divided into ADCGAINH (6 bits) and ADCGAINL (8 bits).

The offset calibration coefficient compensates for dc offset errors in both the ADC and the input signal. Increasing the offset coefficient compensates for positive offset, and effectively pushes the ADC transfer function down. Decreasing the offset coefficient compensates for negative offset, and effectively pushes the ADC transfer function up. The maximum offset that can be compensated is typically ±5% of V_{REF}, which equates to typically ±125 mV with a 2.5 V reference.

Similarly, the gain calibration coefficient compensates for dc gain errors in both the ADC and the input signal. Increasing the gain coefficient compensates for a smaller analog input signal range and scales the ADC transfer function up, effectively increasing the slope of the transfer function. Decreasing the gain coefficient compensates for a larger analog input signal range and scales the ADC transfer function down, effectively decreasing the slope of the transfer function. The maximum analog input signal range for which the gain coefficient can compensate is $1.025 \times V_{REF}$, and the minimum input range is $0.975 \times V_{REF}$, which equates to typically ±2.5% of the reference voltage.

CALIBRATING THE ADC

Two hardware calibration modes are provided, which can be easily initiated by user software. The ADCCON3 SFR is used to calibrate the ADC. Bit 1 (typical) and CS3 to CS0 (ADCCON2) set up the calibration modes.

Device calibration can be initiated to compensate for significant changes in operating condition frequency, analog input range, reference voltage, and supply voltages. In this calibration mode, offset calibration uses internal AGND selected via ADCCON2 register Bits CS3 to CS0 (1011), and gain calibration uses internal V_{REF} selected by Bits CS3 to CS0 (1100). Offset calibration should be executed first, followed by gain calibration. System calibration can be initiated to compensate for both internal and external system errors. To perform system calibration by using an external reference, tie the system ground and reference to any two of the six selectable inputs. Enable external reference mode (ADCCON1.6). Select the channel connected to AGND via Bits CS3 to CS0 and perform system offset calibration. Select the channel connected to V_{REF} via Bits CS3 to CS0 and perform system gain calibration.

A 4 kByte Flash/EE data memory space is also provided on-chip. This may be used as a general-purpose nonvolatile scratchpad area. User access to this area is via a group of six SFRs. This space can be programmed at a byte level, although it must first be erased in 4-byte pages.

Flash/EE Memory Reliability

The Flash/EE program and data memory arrays on the parts are fully qualified for two key Flash/EE memory characteristics: Flash/EE memory cycling endurance and Flash/EE memory data retention.

Endurance quantifies the ability of the Flash/EE memory to be cycled through many program, read, and erase cycles. In real terms, a single endurance cycle is composed of four independent, sequential events, defined as

1. Initial page erase sequence.
2. Read/verify sequence a single Flash/EE.
3. Byte program sequence memory.
4. Second read/verify sequence endurance cycle.

In reliability qualification, every byte in both the program and data Flash/EE memory is cycled from 00H to FFH until a first fail is recorded, signifying the endurance limit of the on-chip Flash/EE memory.

As indicated in the Specifications table, the parts' Flash/EE memory endurance qualification has been carried out in accordance with JEDEC Retention Lifetime Specification A117 over the industrial temperature range of –40°C to +25°C and +25°C to +85°C. The results allow the specification of a minimum endurance figure over supply and over temperature of 100,000 cycles, with an endurance figure of 700,000 cycles being typical of operation at 25°C.

Retention quantifies the ability of the Flash/EE memory to retain its programmed data over time. Again, the parts have been qualified in accordance with the formal JEDEC Retention Lifetime Specification (A117) at a specific junction temperature (T_J = 55°C). As part of this qualification procedure, the Flash/EE memory is cycled to its specified endurance limit, described previously, before data retention is characterized. This means that the Flash/EE memory is guaranteed to retain its data for its fully specified retention lifetime every time the Flash/EE memory is reprogrammed. Also note that retention lifetime, based on an activation energy of 0.6 eV, derates with T_J as shown in Figure 38.

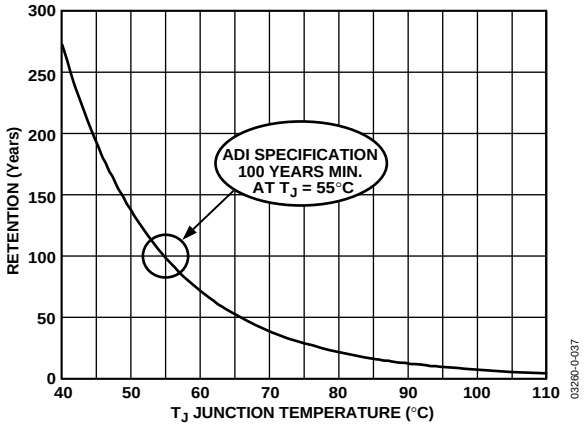

Figure 38. Flash/EE Memory Data Retention

Using the Flash/EE Program Memory

The 62 kByte Flash/EE program memory array is mapped into the lower 62 kBytes of the 64 kByte program space addressable by the parts, and is used to hold user code in typical applications. The program Flash/EE memory array can be programmed in three ways:

Serial Downloading (In-Circuit Programming)

The parts facilitate code download via the standard UART serial port. The parts enter serial download mode after a reset or power cycle if the $\overline{\text{PSEN}}$ pin is pulled low through an external 1 kΩ resistor. Once in serial download mode, the user can download code to the full 62 kBytes of Flash/EE program memory while the device is in-circuit in its target application hardware.

A PC serial download executable is provided as part of the ADuC841/ADuC842 QuickStart development system. The serial download protocol is detailed in MicroConverter Application Note uC004.

Parallel Programming

Parallel programming mode is fully compatible with conventional third party flash or EEPROM device programmers. In this mode, Ports P0, P1, and P2 operate as the external data and address bus interface, ALE operates as the write enable strobe, and Port P3 is used as a general configuration port, which configures the device for various program and erase operations during parallel programming. The high voltage (12 V) supply required for flash programming is generated using on-chip charge pumps to supply the high voltage program lines. The complete parallel programming specification is available on the MicroConverter home page at www.analog.com/microconverter.

ADuC842/ADuC843 Configuration SFR (CFG842)

The CFG842 SFR contains the necessary bits to configure the internal XRAM, external clock select, PWM output selection, DAC buffer, and the extended SP for both the ADuC842 and the ADuC843. By default, it configures the user into 8051 mode, that is, extended SP is disabled and internal XRAM is disabled. On the ADuC841, this register is the CFG841 register and is described on the next page.

CFG842	ADuC842/ADuC843 Config SFR
SFR Address	AFH
Power-On Default	00H
Bit Addressable	No

Table 14. CFG842 SFR Bit Designations

Bit No.	Name	Description
7	EXSP	Extended SP Enable. When set to 1 by the user, the stack rolls over from SPH/SP = 00FFH to 0100H. When set to 0 by the user, the stack rolls over from SP = FFH to SP = 00H.
6	PWPO	PWM Pin Out Selection. Set to 1 by the user to select P3.4 and P3.3 as the PWM output pins. Set to 0 by the user to select P2.6 and P2.7 as the PWM output pins.
5	DBUF	DAC Output Buffer. Set to 1 by the user to bypass the DAC output buffer. Set to 0 by the user to enable the DAC output buffer.
4	EXTCLK	Set by the user to 1 to select an external clock input on P3.4. Set by the user to 0 to use the internal PLL clock.
3	RSVD	Reserved. This bit should always contain 0.
2	RSVD	Reserved. This bit should always contain 0.
1	MSPI	Set to 1 by the user to move the SPI functionality of MISO, MOSI, and SCLOCK to P3.3, P3.4, and P3.5, respectively. Set to 0 by the user to leave the SPI functionality as usual on MISO, MOSI, and SCLOCK pins.
0	XRAMEN	XRAM Enable Bit. When set to 1 by the user, the internal XRAM is mapped into the lower 2 kBytes of the external address space. When set to 0 by the user, the internal XRAM is not accessible, and the external data memory is mapped into the lower 2 kBytes of external data memory.

ON-CHIP PLL

The ADuC842 and ADuC843 are intended for use with a 32.768 kHz watch crystal. A PLL locks onto a multiple (512) of this to provide a stable 16.78 MHz clock for the system. The ADuC841 operates directly from an external crystal. The core can operate at this frequency or at binary submultiples of it to allow power saving in cases where maximum core performance is not required. The default core clock is the PLL clock divided by 8 or 2.097152 MHz. The ADC clocks are also derived from the PLL clock, with the modulator rate being the same as the crystal oscillator frequency. The preceding choice of frequencies ensures that the modulators and the core are synchronous, regardless of the core clock rate. The PLL control register is PLLCON.

At 5 V the core clock can be set to a maximum of 16.78 MHz, while at 3 V the maximum core clock setting is 8.38 MHz. The CD bits should not be set to 0 on a 3 V part.

Note that on the ADuC841, changing the CD bits in PLLCON causes the core speed to change. The core speed is crystal freq/2^{CD}. The other bits in PLLCON are reserved in the case of the ADuC841 and should be written with 0.

PLLCON PLL	**Control Register**
SFR Address	D7H
Power-On Default	53H
Bit Addressable	No

Table 17. PLLCON SFR Bit Designations

Bit No.	Name	Description			
7	OSC_PD	Oscillator Power-Down Bit. Set by the user to halt the 32 kHz oscillator in power-down mode. Cleared by the user to enable the 32 kHz oscillator in power-down mode. This feature allows the TIC to continue counting even in power-down mode.			
6	LOCK	PLL Lock Bit. This is a read-only bit. Set automatically at power-on to indicate that the PLL loop is correctly tracking the crystal clock. If the external crystal subsequently becomes disconnected, the PLL rails. Cleared automatically at power-on to indicate that the PLL is not correctly tracking the crystal clock. This may be due to the absence of a crystal clock or an external crystal at power-on. In this mode, the PLL output can be 16.78 MHz ±20%.			
5	----	Reserved. Should be written with 0.			
4	----	Reserved. Should be written with 0.			
3	FINT	Fast Interrupt Response Bit. Set by the user enabling the response to any interrupt to be executed at the fastest core clock frequency, regardless of the configuration of the CD2–0 bits (see below). Once user code has returned from an interrupt, the core resumes code execution at the core clock selected by the CD2–0 bits. Cleared by the user to disable the fast interrupt response feature.			
2	CD2	CPU (Core Clock) Divider Bits.			
1	CD1	This number determines the frequency at which the microcontroller core operates.			
0	CD0	CD2	CD1	CD0	Core Clock Frequency (MHz)
		0	0	0	16.777216
		0	0	1	8.388608
		0	1	0	4.194304
		0	1	1	2.097152 (Default Core Clock Frequency)
		1	0	0	1.048576
		1	0	1	0.524288
		1	1	0	0.262144
		1	1	1	0.131072

Using the SPI Interface

Depending on the configuration of the bits in the SPICON SFR shown in Table 19, the ADuC841/ADuC842/ADuC843 SPI interface transmits or receives data in a number of possible modes. Figure 54 shows all possible SPI configurations for the parts, and the timing relationships and synchronization between the signals involved. Also shown in this figure is the SPI interrupt bit (ISPI) and how it is triggered at the end of each byte-wide communication.

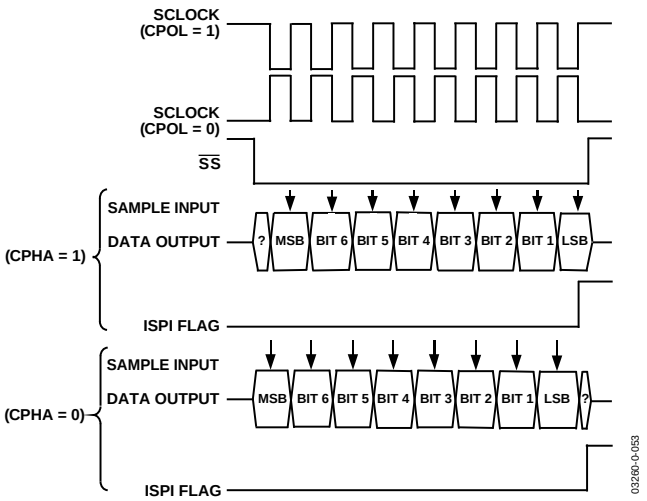

Figure 54. SPI Timing, All Modes

SPI Interface—Master Mode

In master mode, the SCLOCK pin is always an output and generates a burst of eight clocks whenever user code writes to the SPIDAT register. The SCLOCK bit rate is determined by SPR0 and SPR1 in SPICON. Also note that the $\overline{SS}$ pin is not used in master mode. If the parts need to assert the $\overline{SS}$ pin on an external slave device, a port digital output pin should be used.

In master mode, a byte transmission or reception is initiated by a write to SPIDAT. Eight clock periods are generated via the SCLOCK pin and the SPIDAT byte being transmitted via MOSI. With each SCLOCK period, a data bit is also sampled via MISO. After eight clocks, the transmitted byte is completely transmitted, and the input byte waits in the input shift register. The ISPI flag is set automatically, and an interrupt occurs if enabled. The value in the shift register is latched into SPIDAT.

SPI Interface—Slave Mode

In slave mode, SCLOCK is an input. The $\overline{SS}$ pin must also be driven low externally during the byte communication. Transmission is also initiated by a write to SPIDAT. In slave mode, a data bit is transmitted via MISO, and a data bit is received via MOSI through each input SCLOCK period. After eight clocks, the transmitted byte is completely transmitted, and the input byte waits in the input shift register. The ISPI flag is set automatically, and an interrupt occurs if enabled. The value in the shift register is latched into SPIDAT only when the transmission/reception of a byte has been completed. The end of transmission occurs after the eighth clock has been received if CPHA = 1, or when $\overline{SS}$ returns high if CPHA = 0.

I²C COMPATIBLE INTERFACE

The ADuC841/ADuC842/ADuC843 support a fully licensed I²C serial interface. The I²C interface is implemented as a full hardware slave and software master. SDATA is the data I/O pin, and SCLOCK is the serial clock. These two pins are shared with the MOSI and SCLOCK pins of the on-chip SPI interface. To enable the I²C interface, the SPI interface must be turned off (see SPE in Table 19) or the SPI interface must be moved to P3.3, P3.4, and P3.5 via the CFG841.1/CFG842.1 bit. Application Note uC001 describes the operation of this interface as implemented and is available from the MicroConverter website at www.analog.com/microconverter.

Three SFRs are used to control the I²C interface and are described in the following tables.

I2CCON	I²C Control Register
SFR Address	E8H
Power-On Default	00H
Bit Addressable	Yes

Table 20. I2CCON SFR Bit Designations, Master Mode

Bit No.	Name	Description
7	MDO	I²C Software Master Data Output Bit (Master Mode Only). This data bit is used to implement a master I²C transmitter interface in software. Data written to this bit is output on the SDATA pin if the data output enable (MDE) bit is set.
6	MDE	I²C Software Master Data Output Enable Bit (Master Mode Only). Set by the user to enable the SDATA pin as an output (Tx). Cleared by the user to enable the SDATA pin as an input (Rx).
5	MCO	I²C Software Master Clock Output Bit (Master Mode Only). This data bit is used to implement a master I²C transmitter interface in software. Data written to this bit is output on the SCLOCK pin.
4	MDI	I²C Software Master Data Input Bit (Master Mode Only). This data bit is used to implement a master I²C receiver interface in software. Data on the SDATA pin is latched into this bit on SCLOCK if the data output enable (MDE) bit is 0.
3	I2CM	I²C Master/Slave Mode Bit. Set by the user to enable I²C software master mode. Cleared by the user to enable I²C hardware slave mode.
2	----	Reserved.
1	----	Reserved.
0	----	Reserved.

Table 21. I2CCON SFR Bit Designations, Slave Mode

Bit No.	Name	Description
7	I2CSI	I²C Stop Interrupt Enable Bit. Set by the user to enable I²C stop interrupts. If set, a stop bit that follows a valid start condition generates an interrupt. Cleared by the user to disable I²C stop interrupts.
6	I2CGC	I²C General Call Status Bit. Set by hardware after receiving a general call address. Cleared by the user.
5	I2CID1	I²C Interrupt Decode Bits.
4	I2CID0	Set by hardware to indicate the source of an I²C interrupt. 00 Start and Matching Address. 01 Repeated Start and Matching Address. 10 User Data. 11 Stop after a Start and Matching Address.
3	I2CM	I²C Master/Slave Mode Bit. Set by the user to enable I²C software master mode. Cleared by the user to enable I²C hardware slave mode.

MOSI is shared with P3.3 and, as such, has the same configuration as the one shown in Figure 61.

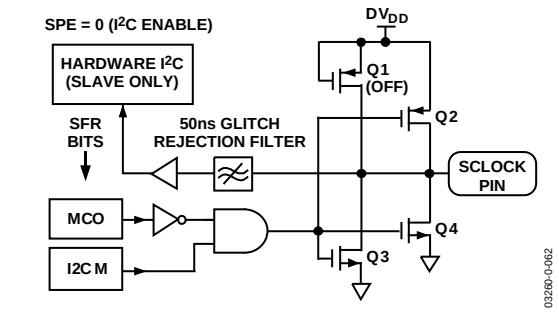

Figure 63. SCLOCK Pin I/O Functional Equivalent in I²C Mode

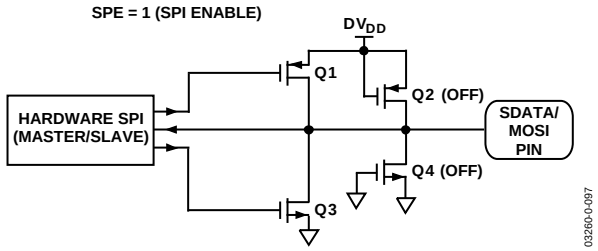

Figure 64. SDATA/MOSI Pin I/O Functional Equivalent in SPI Mode

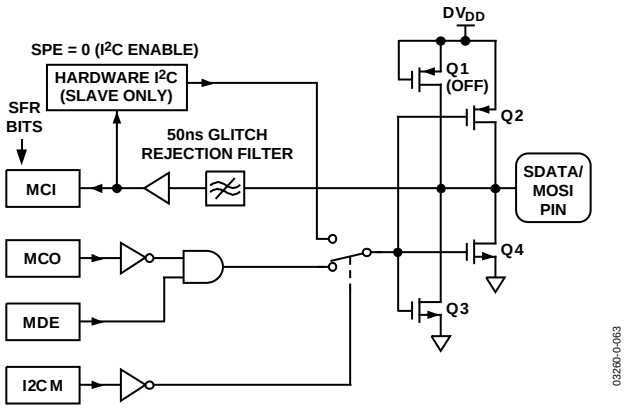

Figure 65. SDATA/MOSI Pin I/O Functional Equivalent in I²C Mode

Read-Modify-Write Instructions

Some 8051 instructions that read a port read the latch while others read the pin. The instructions that read the latch rather than the pins are the ones that read a value, possibly change it, and then rewrite it to the latch. These are called read-modify-write instructions, which are listed below. When the destination operand is a port or a port bit, these instructions read the latch rather than the pin.

Table 28. Read-Write-Modify Instructions

Instruction	Description
ANL	Logical AND, for example, ANL P1, A
ORL	(Logical OR, for example, ORL P2, A
XRL	(Logical EX-OR, for example, XRL P3, A
JBC	Jump if Bit = 1 and clear bit, for example, JBC P1.1, LABEL
CPL	Complement bit, for example, CPL P3.0
INC	Increment, for example, INC P2
DEC	Decrement, for example, DEC P2
DJNZ	Decrement and Jump if Not Zero, for example, DJNZ P3, LABEL
MOV PX.Y, C[1]	Move Carry to Bit Y of Port X
CLR PX.Y[1]	Clear Bit Y of Port X
SETB PX.Y[1]	Set Bit Y of Port X

[1] These instructions read the port byte (all 8 bits), modify the addressed bit, and then write the new byte back to the latch.

Read-modify-write instructions are directed to the latch rather than to the pin to avoid a possible misinterpretation of the voltage level of a pin. For example, a port pin might be used to drive the base of a transistor. When 1 is written to the bit, the transistor is turned on. If the CPU then reads the same port bit at the pin rather than the latch, it reads the base voltage of the transistor and interprets it as a Logic 0. Reading the latch rather than the pin returns the correct value of 1.

TIMER/COUNTER OPERATING MODES

The following sections describe the operating modes for Timer/Counter 2. The operating modes are selected by bits in the T2CON SFR, as shown in Table 32.

Table 32. T2CON Operating Modes

RCLK (or) TCLK	CAP2	TR2	Mode
0	0	1	16-Bit Autoreload
0	1	1	16-Bit Capture
1	X	1	Baud Rate
X	X	0	OFF

16-Bit Autoreload Mode

Autoreload mode has two options that are selected by Bit EXEN2 in T2CON. If EXEN2 = 0, then when Timer 2 rolls over, it not only sets TF2 but also causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2L and RCAP2H, which are preset by software. If EXEN2 = 1, then Timer 2 still performs the above, but with the added feature that a 1-to-0 transition at external input T2EX also triggers the 16-bit reload and set EXF2. Autoreload mode is illustrated in Figure 70.

16-Bit Capture Mode

Capture mode also has two options that are selected by bit EXEN2 in T2CON. If EXEN2 = 0, then Timer 2 is a 16-bit timer or counter that, upon overflowing, sets Bit TF2, the Timer 2 overflow bit, which can be used to generate an interrupt. If EXEN2 = 1, then Timer 2 still performs the above, but a l-to-0 transition on external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. In addition, the transition at T2EX causes Bit EXF2 in T2CON to be set, and EXF2, like TF2, can generate an interrupt. Capture mode is illustrated in Figure 71. The baud rate generator mode is selected by RCLK = 1 and/or TCLK = 1.

In either case, if Timer 2 is being used to generate the baud rate, the TF2 interrupt flag does not occur. Therefore, Timer 2 interrupts does not occur, so they do not have to be disabled. In this mode, the EXF2 flag, however, can still cause interrupts, which can be used as a third external interrupt. Baud rate generation is described as part of the UART serial port operation in the following section.

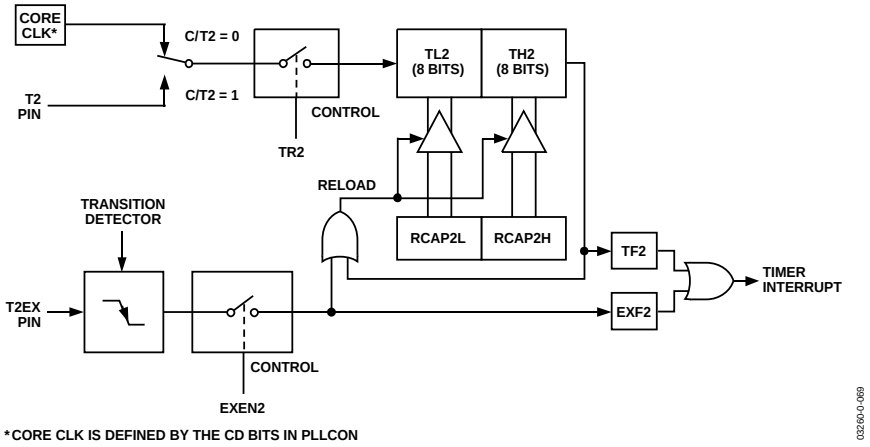

Figure 70. Timer/Counter 2, 16-Bit Autoreload Mode

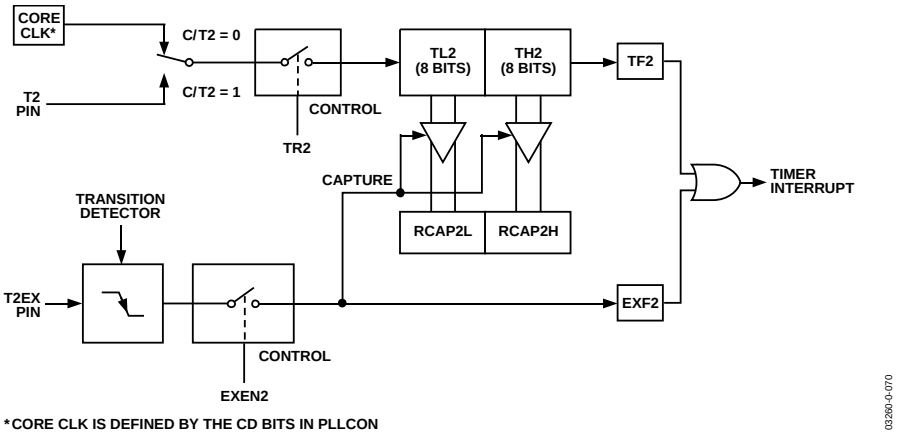

Figure 71. Timer/Counter 2, 16-Bit Capture Mode

HARDWARE DESIGN CONSIDERATIONS

This section outlines some of the key hardware design considerations that must be addressed when integrating the ADuC841/ADuC842/ADuC843 into any hardware system.

Clock Oscillator

The clock source for the parts can be generated by the internal PLL or by an external clock input. To use the internal PLL, connect a 32.768 kHz parallel resonant crystal between XTAL1 and XTAL2, and connect a capacitor from each pin to ground as shown in Figure 75. The parts contain an internal capacitance of 18 pF on the XTAL1 and XTAL2 pins, which is sufficient for most watch crystals. This crystal allows the PLL to lock correctly to give an f_{VCO} of 16.777216 MHz. If no crystal is present, the PLL free runs, giving an fVCO of 16.7 MHz ±20%. In this mode, the CD bits are limited to CD = 1, giving a max core clock of 8.38 MHz. This is useful if an external clock input is required. The part powers up and the PLL free runs; the user then writes to the CFG842 SFR in software to enable the external clock input on P3.4. Note that double the required clock must be provided externally since the part runs at CD = 1. A better solution is to use the ADuC841 with the external clock.

For the ADuC841, connect the crystal in the same manner; external capacitors should be connected as per the crystal manufacturer's recommendations. A minimum capacitance of 20 pF is recommended on XTAL1 and XTAL2. The ADuC841 does not operate if no crystal is present.

An external clock may be connected as shown in Figure 76 and Figure 77.

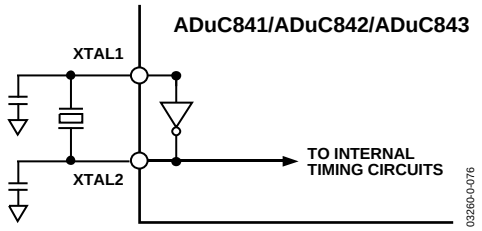

Figure 75. External Parallel Resonant Crystal Connections

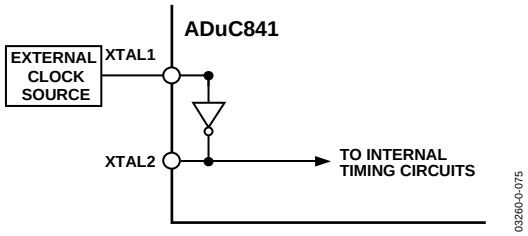

Figure 76. Connecting an External Clock Source (ADuC841)

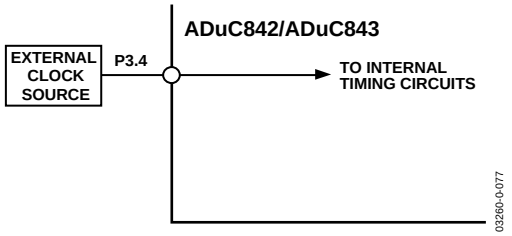

Figure 77. Connecting an External Clock Source (ADuC842/ADuC843)

Whether using the internal PLL or an external clock source, the specified operational clock speed range of the devices is 400 kHz to 16.777216 MHz, (20 MHz, ADuC841). The core itself is static, and functions all the way down to dc. But at clock speeds slower that 400 kHz, the ADC can no longer function correctly. Therefore, to ensure specified operation, use a clock frequency of at least 400 kHz and no more than 20 MHz.

External Memory Interface

In addition to its internal program and data memories, the parts can access up to 16 MBytes of external data memory (SRAM). Note that the parts cannot access external program memory.

Figure 78 shows a hardware configuration for accessing up to 64 kBytes of external RAM. This interface is standard to any 8051 compatible MCU.

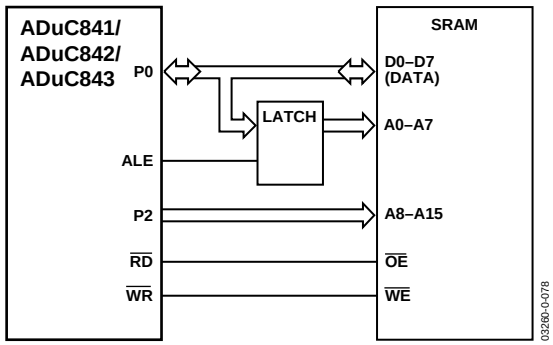

Figure 78. External Data Memory Interface (64 kBytes Address Space)

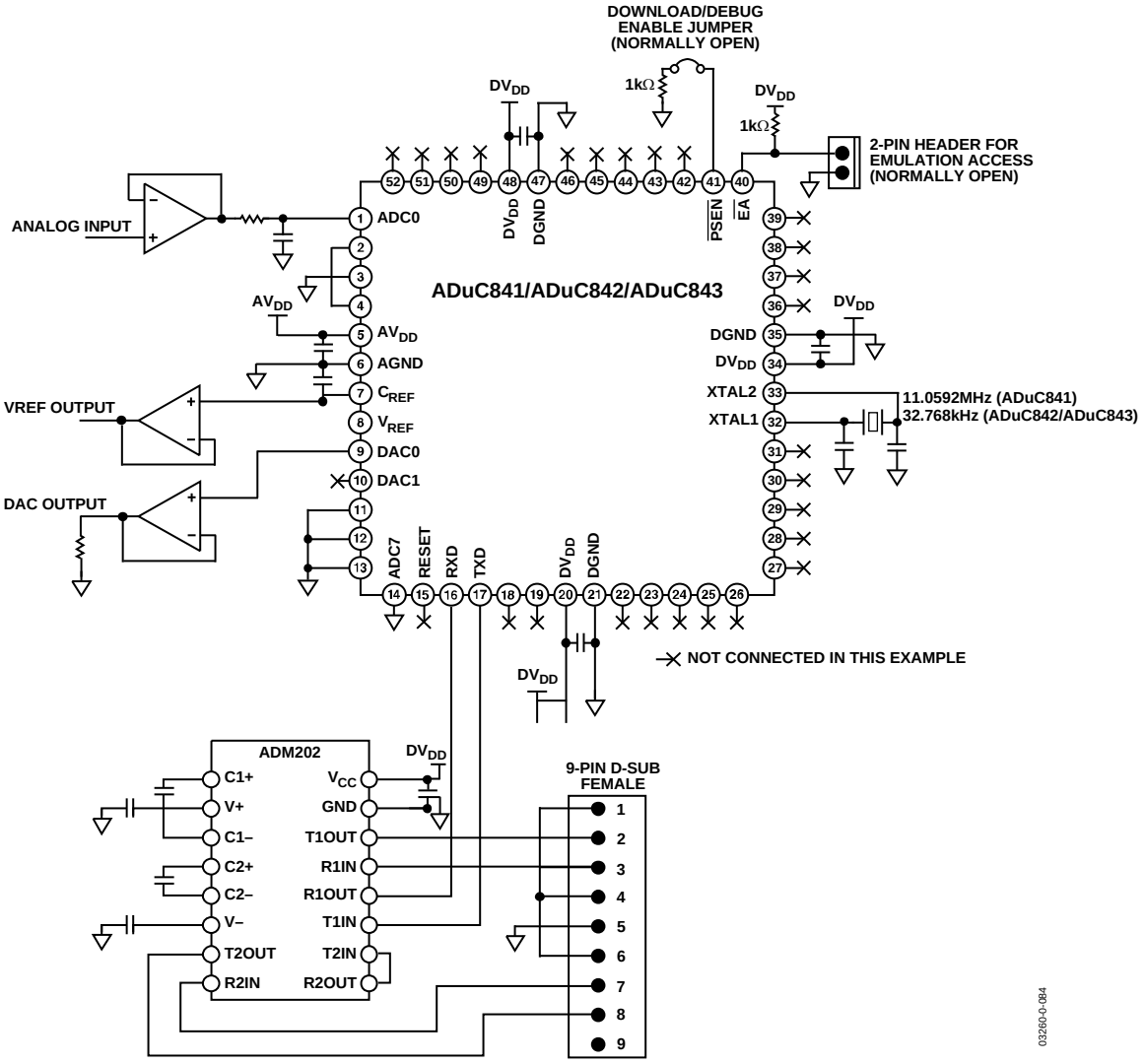

Figure 85. Example System (PQFP Package), DACs Not Present on ADuC843

OTHER HARDWARE CONSIDERATIONS

To facilitate in-circuit programming, plus in-circuit debug and emulation options, users need to implement some simple connection points in their hardware to allow easy access to download, debug, and emulation modes.

In-Circuit Serial Download Access

Nearly all ADuC841/ADuC842/ADuC843 designs want to take advantage of the in-circuit reprogrammability of the chip. This is accomplished by a connection to the ADuC841/ADuC842/ADuC843's UART, which requires an external RS-232 chip for level translation if downloading code from a PC. Basic configuration of an RS-232 connection is illustrated in Figure 85 with a simple ADM202 based circuit. If users would rather not design an RS-232 chip onto a board, refer to Application Note uC006, *A 4-Wire UART-to-PC Interface*, (at www.analog.com/microconverter) for a simple (and zero-cost-per-board) method of gaining in-circuit serial download access to the part.

In addition to the basic UART connections, users also need a way to trigger the chip into download mode. This is accomplished via a 1 kΩ pull-down resistor that can be jumpered onto the $\overline{\text{PSEN}}$ pin, as shown in Figure 85. To get the part into download mode, simply connect this jumper and power-cycle the device (or manually reset the device, if a manual reset button is available), and it is then ready to serially receive a new program. With the jumper removed, the device comes up in normal mode (and runs the program) whenever power is cycled or RESET is toggled.

Parameter		16 MHz Core Clk		8 MHz Core Clock		
EXTERNAL DATA MEMORY READ CYCLE		**Min**	**Max**	**Min**	**Max**	**Unit**
t_{RLRH}	$\overline{RD}$ Pulse Width	60		125		ns
t_{AVLL}	Address Valid after ALE Low	60		120		ns
t_{LLAX}	Address Hold after ALE Low	145		290		ns
t_{RLDV}	$\overline{RD}$ Low to Valid Data In		48		100	Ns
t_{RHDX}	Data and Address Hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	Data Float after $\overline{RD}$		150		625	ns
t_{LLDV}	ALE Low to Valid Data In		170		350	ns
t_{AVDV}	Address to Valid Data In		230		470	ns
t_{LLWL}	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	130		255		ns
t_{AVWL}	Address Valid to $\overline{RD}$ or $\overline{WR}$ Low	190		375		ns
t_{RLAZ}	$\overline{RD}$ Low to Address Float		15		35	ns
t_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE High	60		120		ns

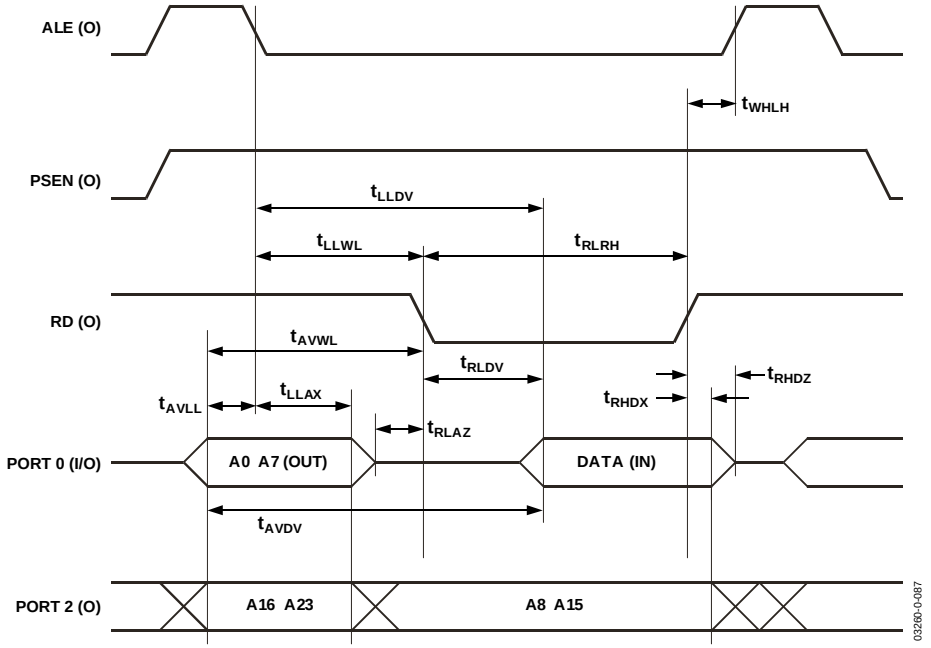

Figure 88. External Data Memory Read Cycle

ORDERING GUIDE

Model[1]	Supply Voltage V_{DD}	User Program Code Space	Temperature Range	Package Description	Package Option
ADuC841BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC841BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC841BCPZ62-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC841BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC842BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC842BCPZ62-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ32-5	5	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ32-3	3	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC842BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADUC843BSZ62-5	5	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC843BSZ62-3	3	62	–40°C to +85°C	52-Lead Plastic Quad Flat Package [MQFP]	S-52-2
ADuC843BCP62Z-5	5	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ62-3	3	62	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCP32Z-5	5	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ32-3	3	32	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ8-5	5	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
ADuC843BCPZ8-3	3	8	–40°C to +85°C	56-Lead Lead Frame Chip Scale Package [LFCSP]	CP-56-11
EVAL-ADuC841QSZ	5			QuickStart Development System for the ADuC841	
EVAL-ADuC841QSPZ	5			QuickStart Plus Development System	
EVAL-ADuC842QSZ	5			QuickStart Development System for the ADuC842 and ADuC843	
EVAL-ADuC842QSPZ	5			QuickStart Plus Development System	
USB-EA-CONVZ				USB to EA Emulator	

[1] The only difference between the ADuC842 and ADuC843devices is the voltage output DACs on the ADuC842; thus, the evaluation system for the ADuC842 is also suitable for the ADuC843.

I²C refers to a communications protocol originally developed by Philips Semiconductors (now NXP Semiconductors).